

INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(Use as many sheets as necessary)</i>		Complete if Known	
		Application Number	Unknown 10/606 539
		Filing Date	Even Date Herewith 6-26-03
		First Named Inventor	Ahn, Kie
		Group Art Unit	Unknown 2813
		Examiner Name	Unknown
Attorney Docket No: 303.533US2			
Sheet 1 of 5			

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		Group Art Unit	Unknown 2813
		Examiner Name	Unknown
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Substitute Disclosure Statement Form (PTO-1449)
 *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached